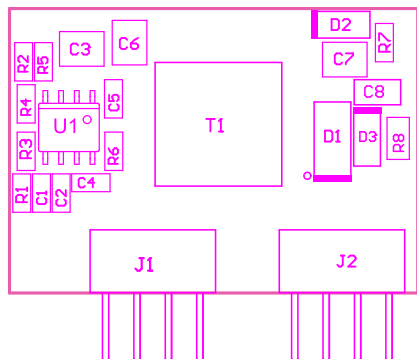


ZZ3 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

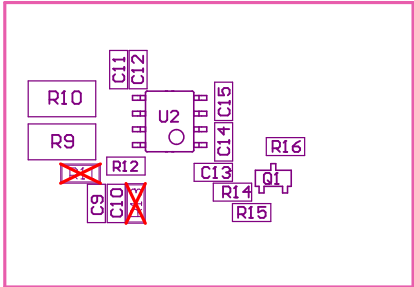
ZZ2 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ1 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01160	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M5 Assembly Top	TID #: TIDA-01160		
PLOT NAME = Top Assembly Drawing	GENERATED : 5/2/2017	1:58:46 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01160	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M6 Assembly Bottom	TID #: TIDA-01160		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 5/2/2017	1:58:47 PM	TEXAS INSTRUMENTS

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